

IN THE CLAIMS:

Please amend the claims as follows:

1-12 (cancelled).

13 (previously presented). An apparatus comprising:

a plurality of MEMS dice formed on a substrate; and

a plurality of caps bonded to the plurality of MEMS dice, the plurality of caps having at least one electrical via extending from a first side of the plurality of caps to a second side of the plurality of caps,

wherein one of the plurality of MEMS dice and one of the plurality of caps forms a device interior and a device exterior, and the electrical via extends from the device interior to the device exterior,

wherein the plurality of caps comprises ceramic and wherein the plurality of caps are coupled to each other by a carrier.

14 (previously presented). The apparatus of claim 13, wherein the electrical via is coupled to a solder ball on the device exterior.

15 (previously presented). An apparatus comprising:

a plurality of MEMS dice formed on a substrate; and

a plurality of caps bonded to the plurality of MEMS dice, the plurality of caps having at least one electrical via extending from a first side of the

plurality of caps to a second side of the plurality of caps,

wherein one of the plurality of MEMS dice and one of the plurality of caps forms a device interior and a device exterior, and the electrical via extends from the device interior to the device exterior,

wherein the plurality of caps comprises a zero-shrink ceramic.

16 (previously presented). A apparatus comprising:

a MEMS die formed on a semiconductor substrate; and

a ceramic cap bonded to the MEMS die to form a hermetically sealed interior, the ceramic cap having at least one electrical via extending from a hermetically sealed interior through the ceramic cap to an exterior,

wherein the ceramic cap is a zero-shrink ceramic.

17 (original). The apparatus of claim 16, wherein the at least one electrical via is coupled to a solder ball on the exterior.

18 (original). The apparatus of claim 16 further comprising:

a circuit board, wherein the circuit board is electrically coupled to the MEMS die by a solder ball and the electrical via.

19 (original). The apparatus of claim 16 further comprising:

an integrated circuit chip, wherein the integrated circuit chip is electrically coupled to the MEMS die by a solder ball and the electrical via.

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20 (cancelled).